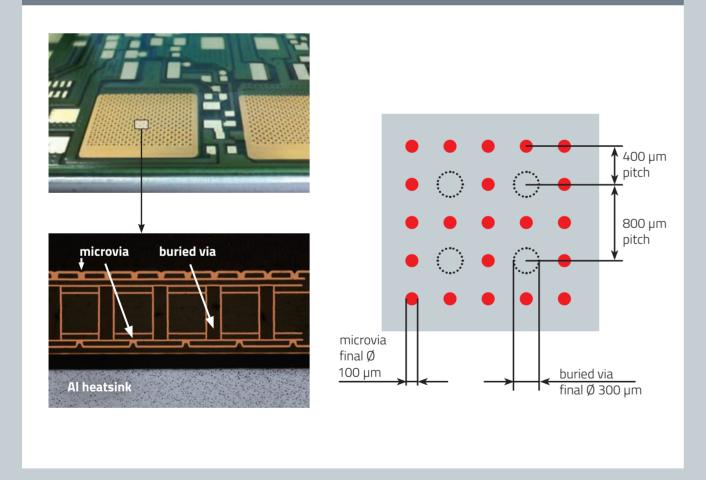


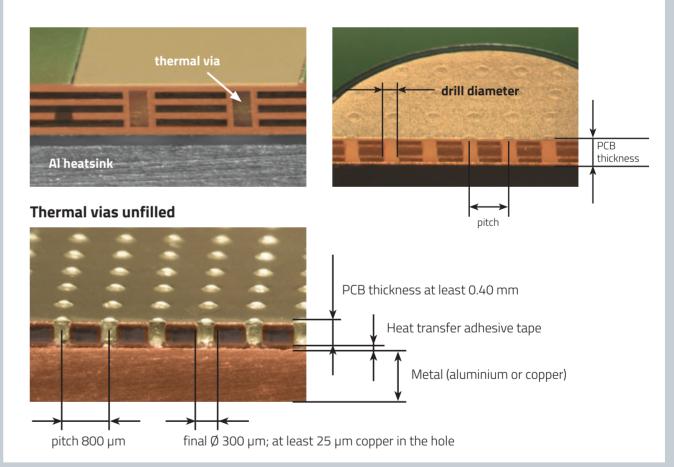
THERMAL MANAGEMENT

Standard Design Rules Microvias Thermal vias pad Ø 650 μm pad Ø 300 μm final Ø 300 µm pad Ø 650 µm final Ø 100 µm final Ø 300 µm 65 µm pitch ≥ 400 µm pitch 800 µm prepreg buried thermal core via prepreg adhesive heatsink

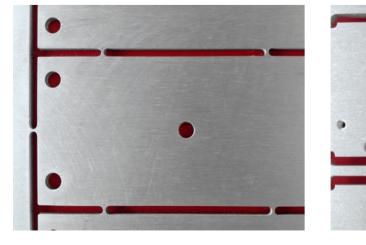
Combination microvia, buried via as thermal vias



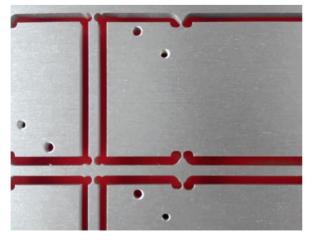
Thermal vias filled (filled & capped via, IPC-4761, Type VII)



Heatsink breaking points

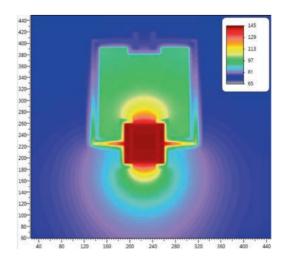


Positive micro edgesThe breaking point is located in the rout path outside the PCB outline.

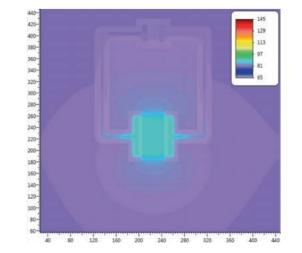


Negative micro edgesBreaking point inside the PCB outline. To ensure stability of the panel additional ribs are required.

Thermal simulation



Printed circuit board 2 layer, 1,6 mm, improved layout, without thermal vias



Printed circuit board 2 layer, with heat sink, 1,6 mm, improved layout, with thermal vias

Thermal simulation of the printed circuit board can help to select the best printed circuit board construction and the optimal layout.